





PIN A1

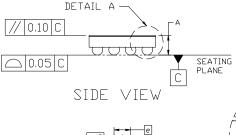
REFERENCE

## WLCSP12 2.00x1.50x0.596 CASE 499AZ ISSUE A

**DATE 03 JUN 2022** 

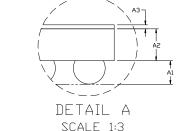
## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009. 1.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION & IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS

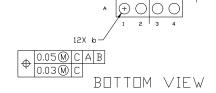


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THP VIFW



DIM	MILLIMETERS				
ויונע	MIN.	N□M,	MAX.		
А	0.541	0.596	0.651		
A1	0.206	0.236	0.266		
A2	0.295	0.320	0.345		
АЗ	0.04 BSC				
b	0.289	0.319	0.349		
D	2.00 BSC				
E	1.50 BSC				
6	0.50 BSC				



## **GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code = Assembly Location

= Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

		-	+	0.50	PITCH
A1					
	0 (	Ð	<b>(</b>	0	_ 0.50 PITCH
_	<del> -</del> 0-0	$\ni$	<del> </del>	-⊕-	<del>   </del>
	⊕ (	С	0	<b></b>	<del>                                     </del>
12X Ø0.25	/				PACKAGE DUTLINE

## RECOMMENDED MOUNTING FOOTPRINT\*

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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